

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	475	(361/715).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/31 14:02
L2	1237	(361/719).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/31 14:03
L4	1169	2 not 1	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/31 14:26
L5	929	(361/707).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/31 14:27
L6	617	5 not 2 not 1	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/31 14:27
S1	1	10/717522	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 08:32
S2	69	("circuit board" or substrate) with "heat pipe" with (case enclosure cover)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 09:01
S3	145	"heat pipe" with (terminal stud contact) with (case enclosure cover)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:21
S4	38	"heat pipe" near3 terminal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:37
S5	25272	"circuit board" with terminal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:37
S6	405	"circuit board" with terminal with thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:40
S7	0	"terminal for circuit board"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:40
S8	11475	"terminal" near3 "circuit board"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:40
S9	7786	"terminal" near2 "circuit board"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:41
S10	93	"terminal".ti. near2 "circuit board".ti.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:48

S11	1708	terminal near3 conductive with "circuit board"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 10:49
S12	53	terminal near3 conductive with "circuit board" with (thermal or heat)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 11:05
S13	964	174/252	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 11:06
S14	265	S13 and terminal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 11:06
S15	308	(thermal or heat) near3 (terminal post stud) with "circuit board"	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 15:37
S16	1976	heat with conductor with case	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 15:41
S17	9792	361/687-720.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 15:42
S18	85	S16 and S17	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 16:45
S19	107	((circuit adj board) or substrate) same (insert\$3 same (heat adj pipe))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/21 17:00
S20	77	((circuit adj board) or substrate) same ((thermally adj connect\$3) same (heat adj pipe))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/21 17:06
S21	70	S20 not S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/21 17:05
S22	181	((circuit adj board) or substrate) same ((housing or enclosure) same (heat adj pipe))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/21 17:07

S23	164	S22 not S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/21 17:13
S24	2	"6212071".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/21 17:13
S25	22	("4118756" "4475145" "4931905" "5179500" "5184283" "5258887" "5343359" "5404272" "5469329" "5506032" "5682943" "5912803" "5946190" "5986887" "6075701").PN. OR ("6212071").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/21 17:14
S26	2	"6696643".pn. "6816377".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 08:32
S27	12	("5258887" "5467251" "6002587" "6025991" "6058013" "6084776" "6101095" "6205028" "6226183" "6434006" "6498726").PN. OR ("6816377"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 08:57
S28	3	("5661902" "5923084" "6101092").PN. OR ("6696643"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 10:49
S29	3	("5661902" "5923084" "6101092").PN. OR ("6696643"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 10:52
S30	3148	(chassis or case or enclosure) with (standoff or spacer or terminal) with (thermal or heat)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 10:54
S31	11132	((361/688,690,700,704,707,710, 715,719,720,794,818) or (165/80.3, 104.33,185)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/24 10:55
S32	141	S30 and S31	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 13:31

S33	49	("5330863" "6387548" "6022805" "6258889" "6352819" "6355586" "6368779" "6700756" "4552206" "5300809" "5623594" "5581443" "5784256" "6152597" "4321423" "4495378" "4509096" "4813128" "4884169" "4994903" "5305185" "5352482" "5500555" "5557500" "5891753" "5923084" "5982616" "5999407" "6013419" "6045975" "6205028" "6212074" "6212074" "4393435" "4630172" "4788766" "4886686" "4910434" "4979074" "5177668" "5357404" "5457342" "5509468" "5603635" "5650081" "5675474" "5699954" "5707247" "5744225" "5777852").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 14:15
S34	1782	"circuit board" with heat with layers	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 15:44
S35	257	S31 and S34	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 14:15
S36	5	("4628409" "4729061" "4792646" "4845308" "4982311").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 14:24
S37	36	"circuit board" with heat with layers with multiple	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 15:53
S38	147	method with "circuit board" with (conductor or layer) with thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 15:59
S39	18	method with "circuit board" with (conductor or layer) with thermal with multilayer	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 16:07
S40	3812	method with "circuit board" with ((thermal or heat)adj3 conductor or layer)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 16:12
S41	1288	S40 and multilayer	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 16:09
S42	1190	S41 and (via or hole or aperature)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 16:10
S43	38	S41 and S31	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 16:11
S44	515	method with "circuit board" with ((thermal or heat)adj3 conductor or layer) with multilayer	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 16:12

S45	181	method with "circuit board" with ((thermal or heat)adj3 conductor or layer) with multilayer with (hole or via or aperature)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 16:23
S46	23	"circuit board" with electrical\$2 with thermal\$2 with simultaneous\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:29
S47	0	"circuit board" with electrical\$2 with thermal\$2 with etch with simultaneous\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:30
S48	3	"circuit board" with electrical\$2 with thermal\$2 with etch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:32
S49	50	"circuit board" with ((electrical\$2 or conductive)adj3 thermal\$2) adj5 layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:57
S50	2	"6621705".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 16:57
S51	9	("4682269" "4720770" "5113315" "5258887" "5659458" "5933324" "5999408" "6212071" "6477054").PN. OR ("6621705").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:02
S52	1	"circuit board" with "circuit path" with (heat or thermal) with ("same time" or simultaneous\$2)	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:04
S53	0	"circuit board" with "circuit path" with (heat or thermal) with ("same layer")	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:05
S54	1	"circuit board" with "conductor" with (heat or thermal) with ("same layer")	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:05
S55	0	"circuit board" with (electrical adj3 conductor) with (heat or thermal) with ("same layer")	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:26

S56	5	"circuit board" with mask with thermal with electrical	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:28
S57	0	"circuit board" with layer with thermal with electrical with seperate	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:28
S58	1	"circuit board" with layer with thermal with electrical with separate	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:53
S59	16	"circuit board" with single with thermal with electrical	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:54
S60	13	"circuit board" with (single adj3 (layer or side)) with thermal	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 17:57
S61	1001	(method or manufacture) with single with thermal with (layer or conductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 17:59
S62	3	S61 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:00
S63	44045	substrate with thermal with layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:01
S64	32250	substrate with electrical with layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:02
S65	4304	S63 and S64	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:01
S66	61	S65 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:01

S67	1447	substrate with electrical with thermal with layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:02
S68	23	S67 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:03